



NOTES:

- MATERIALS:
HOUSING: HIGH TEMP. THERMOPLASTIC PBT, BLACK, UL 94V-0
CONTACTS: 0.014 INCHES (0.35 MILLIMETERS) THICK PHOSPHOR BRONZE PLATED WITH 100 MICROINCHES (2.54 MICROMETERS) MINIMUM THICK TIN IN SOLDER AREA. 15 MICROINCHES (0.38 MICROMETERS) MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE CONTACTS PLATED WITH 50 MICROINCHES (1.27 MICROMETERS) MINIMUM THICK NICKEL.
SHIELDED: 0.0098 INCHES (0.25 MILLIMETERS) THICK COPPER ZINC ALLOY PLATED WITH NICKEL.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F
- UNSPECIFIED TOLERANCE: .XX ±0.25[0.010]
.X ±0.30[0.012]

RoHS Compliant

XMULTIPLE		CONNECTING THE INFORMATION AGE	
MULTIPLE USA 1420 Los Angeles Ave., Suite G, Simi Valley, CA 93065			
THIS DRAWING IS A CONTROLLED DOCUMENT.			DWG NO: XRJDB-S-02-8-8-1-PN5
TITLE: STACKED RJ45 BOTTOM PORT CONNECTORS, W/LED, 8P,8C,SHIELDED, THRU HOLE			DRAWN: BOB
PART NO: XRJDB-S-02-8-8-T-PN1			CHKD: IPIS
	UNIT	SHEET	REV
	mm[Inch]	1 of 1	01
DATE: 4/20/2011			